

N-Channel Enhancement Mode MOSFET

Description

The NVMFS5C682NL uses advanced trench technology

to provide excellent R_{DS(ON)}, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = 60V I_D =30 A

 $R_{DS(ON)}$ < 25m Ω @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

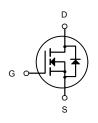
Product ID	Pack	Brand	Qty(PCS)
NVMFS5C682NL	DFN5X6-8L	HXY MOSFET	5000

Absolute Maximum Ratings (T_C=25 ℃ unless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	Drain-Source Voltage 60		
VGS	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	30	А	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	15	А	
IDM	Pulsed Drain Current ²	46	А	
EAS	Single Pulse Avalanche Energy ³	25.5	mJ	
IAS	Avalanche Current	22.6	А	
P _D @T _C =25°C	Total Power Dissipation⁴	34.7	W	
TSTG	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
ReJA	Thermal Resistance Junction-ambient ¹	62	°C/W	
R₀JC	Thermal Resistance Junction-Case ¹	3.6	°C/W	



DFN5X6-8L



N-Channel MOSFET



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.063		V/°C	
В	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =15A		20	25	mΩ	
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V _{GS} =4.5V , I _D =10A		24	20		
$V_{GS(th)}$	Gate Threshold Voltage	\\ -\\ -250\	1.2		2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-5.24		mV/°C	
	Drain Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =25°C			1		
I _{DSS}	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =55°C			5	uA	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	sconductance V _{DS} =5V , I _D =15A		17		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		3.2		Ω	
Qg	Total Gate Charge (4.5V)			12.6			
Q _{gs}	Gate-Source Charge	V _{DS} =48V , V _{GS} =4.5V , I _D =12A		3.2		nC	
Q_{gd}	Gate-Drain Charge			6.3			
T _{d(on)}	Turn-On Delay Time			8			
Tr	Rise Time	V_{DD} =30V , V_{GS} =10V , R_{G} =3.3 Ω ,		14.2		ns	
T _{d(off)}	Turn-Off Delay Time	I _D =10A		24.4			
T _f	Fall Time			4.6			
C _{iss}	Input Capacitance			1378			
C _{oss}	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		86		pF	
C _{rss}	Reverse Transfer Capacitance			64			

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,5}	V =V =0V Force Current			30	Α
I _{SM}	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			46	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	٧

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.1mH,I_{AS}=22.6A
- 4.The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

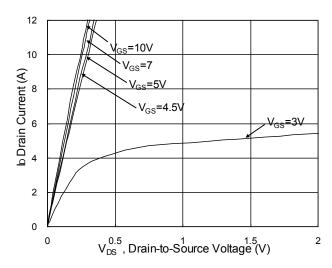


Fig.1 Typical Output Characteristics

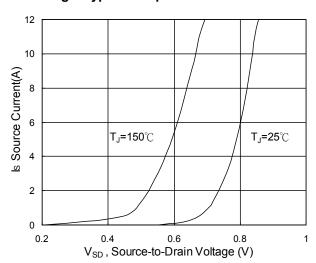


Fig.3 Forward Characteristics of Reverse

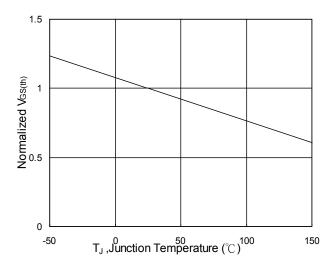


Fig.5 Normalized $V_{\text{GS(th)}}$ v.s T_{J}

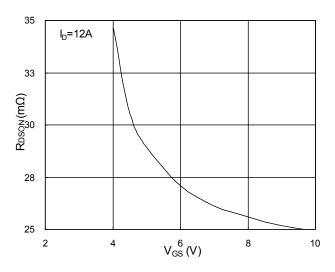


Fig.2 On-Resistance v.s Gate-Source

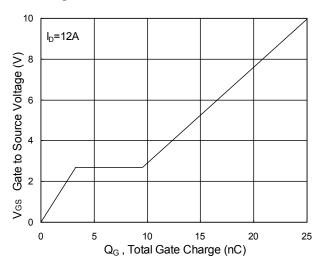


Fig.4 Gate-Charge Characteristics

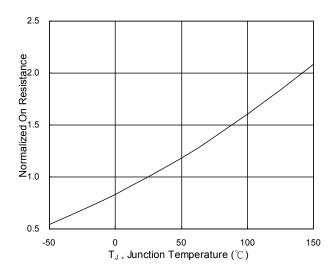
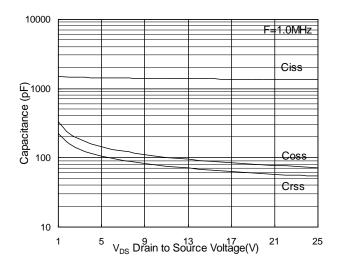


Fig.6 Normalized R_{DSON} v.s T_J



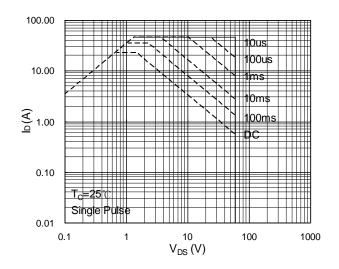


Fig.7 Capacitance

Fig.8 Safe Operating Area

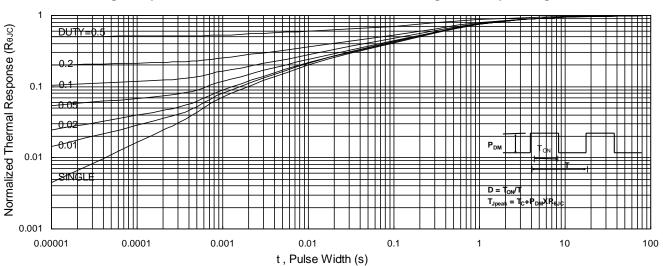


Fig.9 Normalized Maximum Transient Thermal Impedance

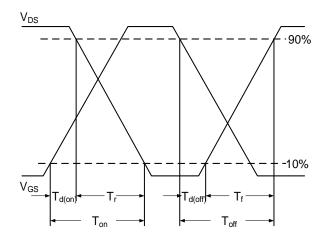


Fig.10 Switching Time Waveform

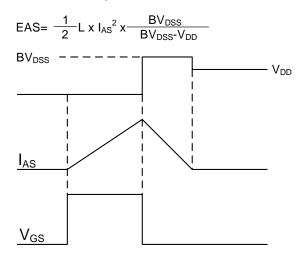
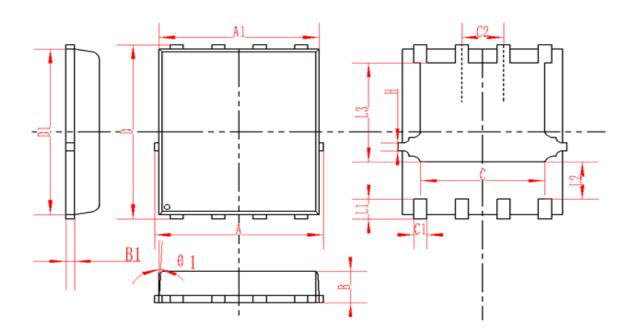


Fig.11 Unclamped Inductive Waveform



DFN5X6-8L Package Information



SYMBOL		MM			INCH		
STIVIDOL	MIN	NOM	MAX	MIN	NOM	MAX	
А	4.95	5	5.05	0.195	0.197	0.199	
A1	4.82	4.9	4.98	0.190	0.193	0.196	
D	5.98	6	6.02	0.235	0.236	0.237	
D1	5.67	5.75	5.83	0.223	0.226	0.230	
В	0.9	0.95	1	0.035	0.037	0.039	
B1	0.254REF			0.010REF			
С	3.95	4	4.05	0.156	0.157	0.159	
C1	0.35	0.4	0.45	0.014	0.016	0.018	
C2		1.27TYP			0.5TYP		
θ1	8°	10°	12°	8°	10°	12°	
L1	0.63	0.64	0.65	0.025	0.025	0.026	
L2	1.2	1.3	1.4	0.047	0.051	0.055	
L3	3.415	3.42	3.425	0.134	0.135	0.135	
Н	0.24	0.25	0.26	0.009	0.010	0.010	



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